Q. Metrology, Inspection, and Yield Enhancement 분과

Room F
봉래 I (6층)

2016년 2월 23일(화) 15:10-17:10
[TF3-Q] Metrology and Inspection I
좌장 : 박병천(한국표준과학연구원), 유형원(SK 하이닉스)

TF3-Q-1 15:10-15:25
요소 트리를 이용한 반도체 SEM 영상의 결함 자동 검출
김성현[1], 김민우[2], 오일석[1,2]
[1]전북대학교 나노과학기술학과, [2]전북대학교 컴퓨터공학과

TF3-Q-2 15:25-15:40
Methodology of Stress Measurement in Copper and Silicon around Through-Silicon via using Nanoindentation and Micro Raman Spectroscopy for 3D IC Interconnects
Jaehyun Kim[1,2], Changhwan Lee[1], Hyungwon Yoo[1], Yeojin Yoon[1], Jinsan Yoo[1], and Seungmin Han[2]
[1]SK hynix Inc., [2]KAIST

TF3-Q-3 15:40-15:55
Identifying the Systematic Failure Mechanism using Volume Diagnostics Methodology
Jeongsu Park[1], Joochan Kim[2], Sunghun Kim[2], and Sunggun Kang[2]
[1]Yield and Failure Analysis, Synopsys, Inc., [2]Process Architecture Team, System LSI, Samsung Electronics Co., Ltd.

TF3-Q-4 15:55-16:10
Methodology Study for Real Cell Overlap Control Under sub-$1_{x\text{-}nm}$ Device Era
Jun-Beom Park, Hong-Boo Lee, Sang-Jun Han, Young-Sik Kim, and Noh-Jung Kwak
R&D Division, SK hynix Inc.

TF3-Q-5 16:10-16:25
Study on the Interferometric Measurements of Wafer Warpage for Correction of Overlay Error
Seung-Il Lim[1,2,3], Jae-Jun Choi[1,2,3], Sung-Min Yoon[1,2,3], Woo Sung Jung[1,2,3], Seung Chul Oh[1,2,3], Jae Yong Lee[1,2,3], and Jaison Kim[1,2,3]
[1]Department of Physics, Myong-ji University, [2]AUROS Technology, [3]KRISS

TF3-Q-6 16:25-16:40
Reliability Analysis of Protective Anodizing Film for Contamination Free Manufacturing under Etching
Je-Boem Song[1,2], Jin-Tae Kim[1], Seung-Su Lee[1], SinHo Choi[1], Seong-Geun Oh[2], and Ju-Young Yun[1]
[1]Vacuum Center, Korea Research Institute of Standards and Science,
[2]Department of Chemical Engineering, Hanyang University